

# JOM Call for papers

An official publication of The Minerals, Metals & Materials Society

Publication Date: *June 2025*

Manuscript Deadline: *December 1, 2024*

## ***Advanced Interconnect and Packaging Technologies***

Advanced progress in microelectronic, optoelectronic, and nano-electronic devices requires developing new materials and technologies to meet the increasing electrical, thermal, mechanical, reliability, performance, and environmental demands placed on interconnects and packaging at all levels. The special topic will address current research in new and existing materials for advanced interconnect and packaging technologies, including Pb-free and low-temperature solder alloys, Ag and Cu sintering, hybrid bonding, 3D packaging and interconnection, wafer-level packaging, and reliability issues.

Original research papers should be 3,000-9,000 words with up to 12 figures maximum; review papers should be 6,000-11,000 words with up to 20 figures maximum.

Detailed author instructions are available at:  
<http://www.tms.org/AuthorTools/>

**Keywords for this topic:** *Advanced Materials; Electronic Materials; Intermetallics; Joining; Thin Films and Interfaces; Reliability*

**Guest Editor(s):** Fan-Yi Ouyang:  
[fyouyang@ess.nthu.edu.tw](mailto:fyouyang@ess.nthu.edu.tw)

**Committee Sponsor(s):** *Electronic Packaging and Interconnection Materials*

If you are interested in submitting a paper, upload your manuscript at  
<https://www.editorialmanager.com/jomj/>

Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

For more information on JOM, please visit [jom.tms.org](http://jom.tms.org)